

## **System Information:**

- **Instrument Provider: BSET EQ Plasma Systems**
- **Gases Used: CF<sub>4</sub>, SF<sub>6</sub>, N<sub>2</sub>**
- **RF Power: 10 – 600W**
- **Maximum flow rates: CF<sub>4</sub> – 200 sccm, SF<sub>6</sub> – 27 sccm, and N<sub>2</sub> – 50 sccm**
- **Wafer Dimensions Allowed : 125 x 125 mm, and 156 x 156 mm**

## **TRAINING PROCESS:**

- **Get approval from your Guide/Faculty Advisor**
- **Contact the System Owner**
- **You need to attend at least two etch sessions with any authorized user**
- **After that you need to attend one or two hands-on session**
- **A test will be taken after that and authorization will be given if cleared, else you need to go for more training sessions before next test**

## **SAFETY HAZARDS & PRECAUTIONS:**

- **Scrubber for this tool is shared with the ICP-RIE system, hence both the tools cannot be run at tandem.**
- **Ensure that the exhaust is turned ON before starting the tool.**
- **Ensure that the scrubber is turned ON before starting the tool.**
- **Always start the tool after consulting the facility team members.**
- **On shutting down the tool, ensure that the scrubber connection is switched back to ICP-RIE.**